



SMC-222-ARP9  
W14.15xD13.40xH1.50

PIN 数(Number of contacts) : 9PIN

操作方式(Operation mode): 自彈式/PUSH PUSH

温度范围(Operating temp): -40°C TO +80°C

额定负荷(Rated load): 0.5A PER PIN.

接触电阻(Contact resistance): 100mΩmax.

绝缘电阻(Insulation resistance):1000MΩ min.

耐电压(Withstand voltage) : 500V AC for 1 min

操作寿命(Operation life): 5,000 Cycles Min

焊接温度(Welding temperature):  $260 \pm 5^{\circ} \text{C}$  5s

焊接方式(Welding mode): 贴片式/SMT

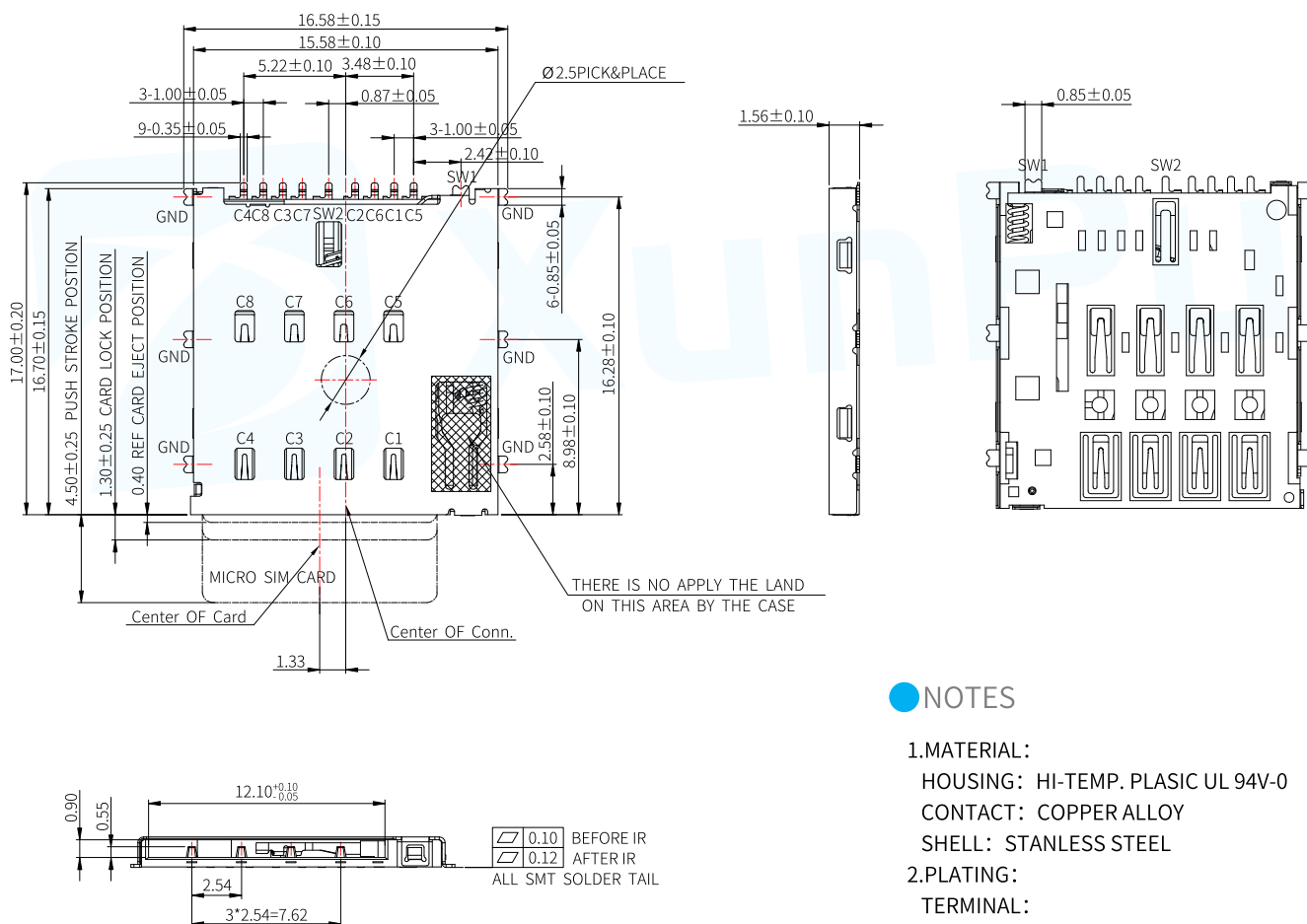
包装方式(Packaging method): 卷带/Tape & Reel (TR)

最小包装(Minimum packing): 1,000/PCS

## 外形尺寸(UNIT:MM) / Size Chart

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更多资料请参考技术选型档!



● NOTES

1.MATERIAL:

HOUSING: HI-TEMP. PLASIC UL 94V-0

CONTACT: COPPER ALLOY

SHELL: STANLESS STEEL

2.PLATING:

TERMINAL:

CONTACT AREA: Au GOLD FLASH

SOLDER AREA: Au GOLD FLASH

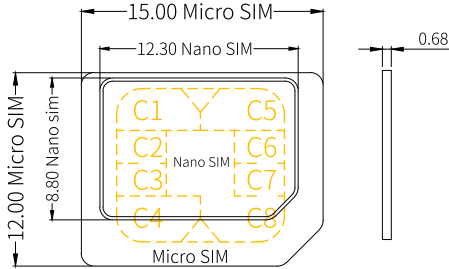
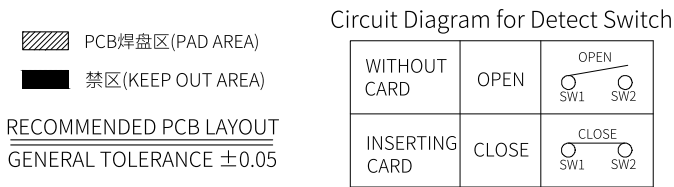
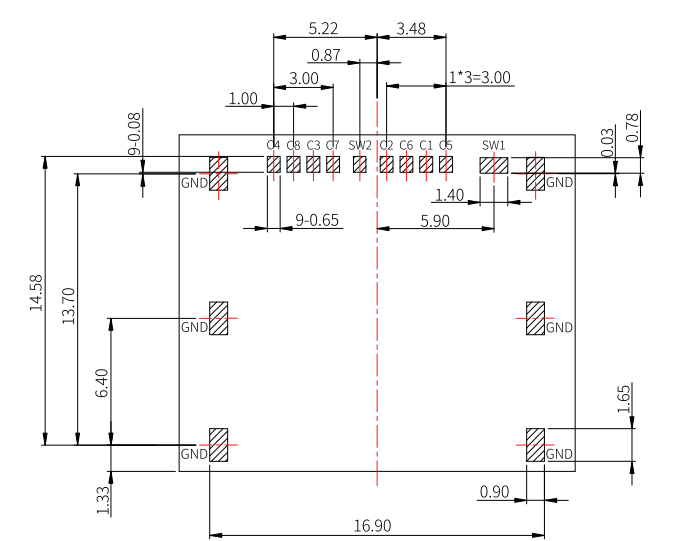
UNDER PLATE: NICKEL

SHELL: NICKEL PLATED OVER ALL

SOLDER AREA: GOLD FLASH

| ITEM | PART NAME | Q'TY | MATERIAL        | DESCRIPTION                              |
|------|-----------|------|-----------------|------------------------------------------|
| 1    | Terminal  | 1    | C5210-EH,T=0.20 | Contact Au:1u",Plating Au:1u",Ni:50u"min |
| 2    | Cover     | 1    | SUS304          | Slider Plating Au:1u",Ni:30u"min         |
| 3    | Slider    | 1    | LCP UL94V-0     | BLACK                                    |
| 4    | Spring    | 1    | SWP-B           | Plating Ni:30u"min                       |
| 5    | Link      | 1    | SUS304          |                                          |
| 6    | Housing   | 1    | LCP UL94V-0     | BLACK                                    |

MICRO SIM



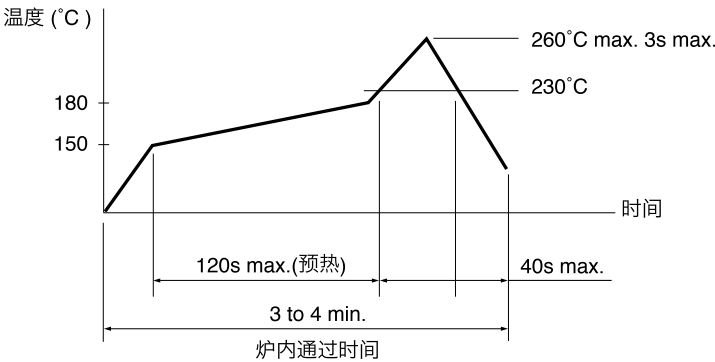
引脚定义/Pin Definition

| SIM PIN ASSIGNMENT |      |      |             |
|--------------------|------|------|-------------|
| PIN#               | NAME | TYPE | DESCRIPTION |
| C1                 | 供电电压 | 1    | VCC         |
| C2                 | 重置   | 1    | RST         |
| C3                 | 时钟   | 1    | CLK         |
| C4                 | 保留项  | 1    | Reserved    |
| C5                 | 接地   | 1    | GND         |
| C6                 | 程序电压 | 1    | VPP         |
| C7                 | 输入输出 | 1    | I/O         |
| C8                 | 保留项  | 1    | Reserved    |

焊接条件 / Welding conditions

回流焊/Reflow soldering

适用表面贴装型产品/Applicable to surface mount products  
 温度分布/Temperature distribution



手焊式/Hand welding

| 项目/Project                        | 条件/condition |
|-----------------------------------|--------------|
| 焊接温度<br>Welding temperature       | 350°C max.   |
| 持续焊接时间<br>Continuous welding time | 3s max.      |
| 焊剂斗容量<br>Flux bucket capacity     | 60W max.     |

浸焊式/Immersion soldering

| 项目/Project                         | 条件/condition                                                                                |
|------------------------------------|---------------------------------------------------------------------------------------------|
| 助焊剂附着量<br>Flux adhesion            | 不附着于零部件贴装面的程度<br>Not attached to the mounting surface of components                         |
| 预热温度<br>Preheating temperature     | 印刷电路板焊接面的周围温度 100°C max.<br>The temperature around the welding surface of PCB is 100 °C max |
| 预热温度时间<br>Preheat temperature time | 60s max.                                                                                    |
| 焊接温度<br>welding temperature        | 260°C max.                                                                                  |
| 焊接浸渍时间<br>Welding immersion time   | 5s max.                                                                                     |
| 焊接次数<br>Welding times              | 2 times max.                                                                                |

- 注:
1. 加热方式:以远红外线上下加热方式。
  2. 温度测量:用Φ0.1~0.2 的 CA(K)或 CC(T)测量位置在焊接连接部(锡/铜箔面)。
  3. 固定方式:采用耐热胶带。